

ER 9.5/5 Planar cores in sets

Series/Type: B65523, B65527

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ER 9.5/5

Planar core B65523

■ To IEC 62317-9

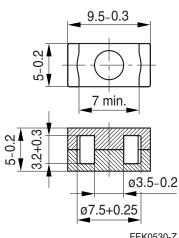
For transformers featuring high inductance and low overall height

■ Delivery mode: sets

Magnetic characteristics (per set)

 $\Sigma I/A = 1.54 \text{ mm}^{-1}$ = 13.6 mm $A_e = 8.81 \text{ mm}^2$ $A_{min} = 7.6 \text{ mm}^2$ $V_e = 120 \text{ mm}^3$

Approx. weight 0.6 g/set



FEK0530-Z

Ungapped

Material	A _L value nH	μ_{e}	Ordering code
N92	660 +30/–20%	811	B65523J0000R092
N87	800 +30/–20%	1000	B65523J0000R087
N97	840 +30/–20%	1032	B65523J0000R097
T38	4500 +40/–30%	5680	B65523J0000Y038

Gapped (A_L values/air gaps examples)

Material	A _L value	s approx. mm	μ_{e}	Ordering code
N49	40 ±5%	0.27	49	B65523J0040J049
N87	100 ±5% 400 ±10%	0.14 0.02	90 491	B65523J0100J087 B65523J0400K087

Other A_L values/air gaps and materials available on request – see Processing remarks on page 4.



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Accessories B65527



SMD coil former with gullwing terminals

Material: GFR liquid crystal polymer (UL 94 V-0, insulation class to IEC 60085:

F ≙ max. operating temperature 155 °C), color code black Vectra E 130i [E106764 (M)], POLYPLASTICS CO LTD

Vectra E 130i [E83005 (M)], CELANESE INTERNATIONAL CORP.

Solderability: to IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s

Resistance to soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s

permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s

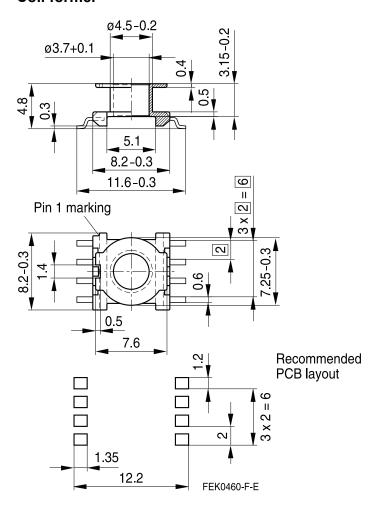
Winding: see Processing notes, 2.1

Yoke

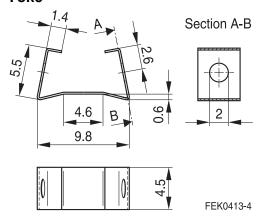
Material: Stainless spring steel (0.1 mm)

Coil former				Ordering code	
Sections	A _N mm ²	I _N mm	A_R value $\mu\Omega$	Terminals	
1	3.23	18.4	196	8	B65527B1008T001
Yoke			·	•	B65527A2000X000

Coil former



Yoke





Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_I value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

EPCOS ferrite accessories have been designed and evaluated only in combination with EPCOS ferrite cores. EPCOS explicitly points out that EPCOS ferrite accessories or EPCOS ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

EPCOS assumes no warranty or reliability for the combination of EPCOS ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



Cautions and warnings

Display of ordering codes for EPCOS products

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_L	Inductance factor; A _L = L/N ²	nH
A_{L1}	Minimum inductance at defined high saturation ($\stackrel{\triangle}{=} \mu_a$)	nH
A_{min}	Minimum core cross section	mm ²
A_N	Winding cross section	mm ²
A_R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m ² , mT
ΔB	Flux density deviation	Vs/m ² , mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
Δ B	Peak value of flux density deviation	Vs/m ² , mT
B_{DC}	DC magnetic flux density	Vs/m ² , mT
B_R	Remanent flux density	Vs/m ² , mT
B_S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
E_a	Activation energy	J
f	Frequency	s ^{−1} , Hz
f _{cutoff}	Cut-off frequency	s−1, Hz
f _{max}	Upper frequency limit	s ^{−1} , Hz
f _{min}	Lower frequency limit	s−1, Hz
f _r	Resonance frequency	s ^{−1} , Hz
f_{Cu}	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H_c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ _i ²	Relative hysteresis coefficient	10 ⁻⁶ cm/A
1	RMS value of current	Α
I_{DC}	Direct current	Α
Î	Peak value of current	Α
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k_3	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

Symbol	Meaning	Unit
Δ L/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L_H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L_s	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P_{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = ω L/R _s = 1/tan δ _L)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R_h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R_i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
S	Total air gap	mm
T	Temperature	°C
ΔT	Temperature difference	K
T_C	Curie temperature	°C
t	Time	S
t_{v}	Pulse duty factor	
$tan \ \delta$	Loss factor	
tan δ_{L}	Loss factor of coil	
tan δ_r	(Residual) loss factor at H $ ightarrow$ 0	
tan δ_{e}	Relative loss factor	
tan δ_{h}	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V_{e}	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z_n	Normalized impedance $ Z _n = Z /N^2 \times \varepsilon (l_e/A_e)$	Ω/mm



Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	
α_{e}	Temperature coefficient of effective permeability	
ϵ_{r}	Relative permittivity	
Φ	Magnetic flux	
η	Efficiency of a transformer	
η _B	Hysteresis material constant	mT-1
η _i	Hysteresis core constant	$A^{-1}H^{-1/2}$
$\lambda_{\sf s}$	Magnetostriction at saturation magnetization	
ı	Relative complex permeability	
ι_0	Magnetic field constant	
la	Relative amplitude permeability	
^l app	Relative apparent permeability	
le	Relative effective permeability	
ιį	Relative initial permeability	
ι _p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
ι _p "	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
ι_{r}	Relative permeability	
ι_{rev}	Relative reversible permeability	
ι _s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
ι _s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
ι_{tot}	Relative total permeability	
	derived from the static magnetization curve	
)	Resistivity	Ω m $^{-1}$
ΣΙ/A	Magnetic form factor	mm ⁻¹
^r Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
ω	Angular frequency; ω = 2 Π f	s ⁻¹

All dimensions are given in mm.





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